What is claimed is:

1. A substrate processing apparatus comprising: a plurality of polishing units comprising discharge valves that discharges water at a predetermined flow rate; a plurality of cleaning units comprising discharge valves that discharges water at a predetermined flow rate; and a controller that controls opening and closing of the discharge valve of each of the plurality of polishing units and the plurality of cleaning units,

wherein the controller controls opening and closing of the discharge valves of the plurality of polishing units and the plurality of cleaning units based on predetermined priority orders allocated to the plurality of polishing units and the plurality of cleaning units, so that a total discharge flow rate from the plurality of polishing units and the plurality of cleaning units is a predetermined flow rate or less.

2. The substrate processing apparatus according to claim 1, wherein discharge from the plurality of polishing units has a higher priority order than discharge from the plurality of cleaning units.

3. The substrate processing apparatus according to claim 1, wherein, when the total discharge flow rate obtained as a result of controlling opening and closing of the discharge valves provided in the plurality of polishing units and the plurality of cleaning units, based on the predetermined priority orders, so that the total discharge flow rate from the plurality of polishing units and the plurality of cleaning units is the predetermined flow rate or less has a capacity to reach the predetermined flow rate, the controller controls opening and closing of the discharge valve of a unit that has a

discharge flow rate equal to or less than the capacity, over the priority orders, so that the total discharge flow rate is an approximate upper limit of the predetermined flow rate.

4. The substrate processing apparatus according to claim 1,

wherein a plurality of the discharge valves are provided for each of the plurality of polishing units, and a plurality of the discharge valves are provided for each of the plurality of cleaning units, and,

based on the predetermined priority orders, the controller controls opening and closing of the plurality of the discharge valves provided in each of the plurality of polishing units and the plurality of cleaning units, by opening or closing all the plurality of the discharge valves, so that the total discharge flow rate from the plurality of polishing units and the plurality of cleaning units is the predetermined flow rate or less.

5. The substrate processing apparatus according to claim 4, wherein, when the total discharge flow rate obtained as a result of performing control by opening or closing all the plurality of the discharge valves provided in each of the plurality of polishing units and the plurality of cleaning units, based on the predetermined priority orders, so that the total discharge flow rate from the plurality of polishing units and the plurality of cleaning units is the predetermined flow rate or less has a capacity to reach the predetermined flow rate, and the capacity is smaller than a discharge flow rate of any of the plurality of polishing units and the plurality of cleaning units, the controller controls opening and closing of each of the plurality of the discharge valves provided in each of the plurality of polishing units and the plurality of cleaning units, so that the total discharge flow rate is an approximate upper limit of the predetermined flow rate.